

**PRODUCT / PROCESS CHANGE INFORMATION**

**1. PCI basic data**

1.1 Company		STMicroelectronics International N.V
1.2 PCI No.	EMBEDDED PROCESSING/25/15894	
1.3 Title of PCI	JSCC (China) LFBGA10x10 package Second level interconnect marking symbol amended for STM32F1x listed products.	
1.4 Product Category	STM32F103x, STM32F105x and STM32F107x	
1.5 Issue date	2025-10-08	

**2. PCI Team**

<b>2.1 Contact supplier</b>	
2.1.1 Name	PIKE EMMA
2.1.2 Phone	+44 1628896111
2.1.3 Email	emma.pike@st.com
<b>2.2 Change responsibility</b>	
2.2.1 Product Manager	Patrick AIDOUNE
2.1.2 Marketing Manager	Veronique BARLATIER
2.1.3 Quality Manager	Pascal NARCHE

**3. Change**

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Methods	Traceability (marking content, company logo, etc)	JSCC (China)

**4. Description of change**

	Old	New
4.1 Description	second level Interconnect symbol is showing category e2 on top marking of the device while solder balls are actually SAC305.	second level Interconnect symbol changed to category e1 on top marking of the device to reflect actual Alloy Composition of SAC305 solder balls. No change in the device hardware composition.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Form: Change is visible on marking area Fit : No change Function : No change Reliability : No change Processability : No change	

**5. Reason / motivation for change**

5.1 Motivation	Symbol used on the Marking is not reflecting the actual alloy composition of the 2nd level interconnect.
5.2 Customer Benefit	SERVICE IMPROVEMENT

**6. Marking of parts / traceability of change**

6.1 Description	Traceability ensured by ST internal tools.
-----------------	--------------------------------------------

**7. Timing / schedule**

7.1 Date of qualification results	2025-10-02
7.2 Intended start of delivery	2025-11-27
7.3 Qualification sample available?	Not Applicable

**8. Qualification / Validation**

8.1 Description	15894 Qualification not applicable.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2025-10-08

9. Attachments (additional documentations)
15894 Public product.pdf 15894 Qualification not applicable.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32F103ZEH6	
	STM32F103ZFH6	
	STM32F103ZGH6	
	STM32F103ZGH6TR	

## **IMPORTANT NOTICE – PLEASE READ CAREFULLY**

Subject to any contractual arrangement in force with you or to any industry standard implemented by us, STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST's terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers' products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2022 STMicroelectronics – All rights reserved